



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-10-07
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	EZDG*S6AA8WL	A	SA1A	2016-10-07
Amount	UoM	Unit type	ST ECOPACK Grade	
8.07	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	2x2x0.75	8	No lead	
Comment	Package: XP MLPD/DFN 2x2x0.75 8L PITCH 0.5; MDF valid for STM6510WCACDG6F			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EZDG*S6AA8WL								
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)			
Die	Other inorganic materials	0.351	mg	supplier	die	Silicon (Si)	7440-21-3		0.327	mg	931624	40520			
				supplier	metallization	Aluminium (Al)	7429-90-5		0.003	mg	8547	372			
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	2849	124			
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	5698	248			
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	25641	1115			
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.009	mg	25641	1115			
Leadframe	Copper & its alloys	2.701	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.436	mg	901888	301859			
				supplier	alloy	Iron (Fe)	7439-89-6		0.057	mg	21103	7063			
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.003	mg	1111	372			
				supplier	alloy	Zinc (Zn)	7440-66-6		0.003	mg	1111	372			
	Nickel (Ni)			supplier	metallization	Nickel (Ni)	7440-02-0		0.024	mg	8886	2974			
				supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	740	248			
	Precious metals			supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	370	124			
				supplier	metallization	Silver (Ag)	7440-22-4		0.175	mg	64791	21685			
	Die attach			Other Organic Materials	0.095	mg	supplier	glue	Epoxyde Bisphenol A Resin	25068-38-6		0.009	mg	94737	1115
							supplier	glue	Fused silica	60676-86-0		0.029	mg	305263	3594
supplier		glue	Ethylidiglycol acetate				112-15-2		0.021	mg	221053	2602			
supplier		glue	Aluminium oxide				1344-28-1		0.019	mg	200000	2354			
supplier		glue	Bisphenol A diglycidyl ether polymer				25036-25-3		0.013	mg	136842	1611			
supplier		glue	Glycol ether ester				Proprietary		0.002	mg	21053	248			
supplier		glue	Diaminodiphenylsulfone				80-08-0		0.002	mg	21053	248			
Bonding wires	Precious metals	0.121	mg	supplier	wire	Gold (Au)	7440-57-5		0.121	mg	1000000	14994			
Encapsulation	Other Organic Materials	4.802	mg	supplier	mold compound	Silica, vitreous	60676-86-0		4.447	mg	926072	551053			
				supplier	mold compound	epoxy resin	85954-11-6		0.192	mg	39983	23792			
				supplier	mold compound	phenol resin	26834-02-6		0.144	mg	29988	17844			
				supplier	mold compound	carbon black	1333-86-4		0.019	mg	3957	2354			